

Building Partnerships in Innovation



About Us

Circuit-Tech Inc. is a customer focused, quick response, and highly complex technology manufacturer of precision printed circuit boards.

- Established in 1982, is one of the oldest and largest privately-held PCB manufacturer in Canada.
- Servicing both Original Equipment Manufacturer's and Electronic Manufacturing Service companies with prototypes, low and medium production volumes.
- Located outside Toronto in Markham, Ontario Canada.
 Occupies over 57,000 square feet of factory space with approximately 59 full-time employees.



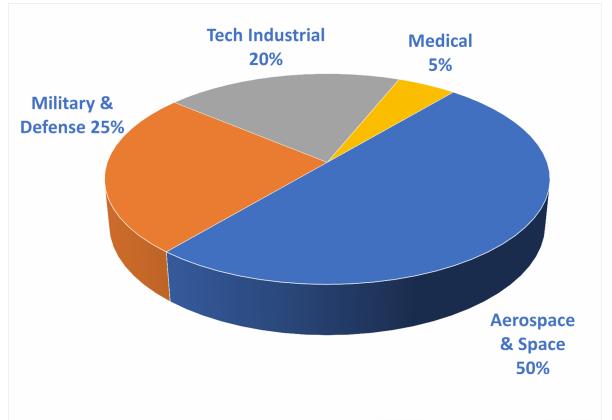
ISO 9001:2015 & AS9100D Certified.



Our Markets



- Aerospace & Space
- Military & Defense
- Tech Industrial
- Medical





Certifications & Accomplishments

AS9100D & ISO 9001:2015



MIL-PRF-31032 Certified



Controlled Goods Program Certified





Certifications & Accomplishments

ITAR Compliant



IPC Member









Certifications & Accomplishments

RoHS Lead Free / REACH Compliant





- GIDEP Government / Industry Data Exchange Program
- Nadcap
- CMMC / NIST SP-800-171
 Cybersecurity Maturity Model Certification







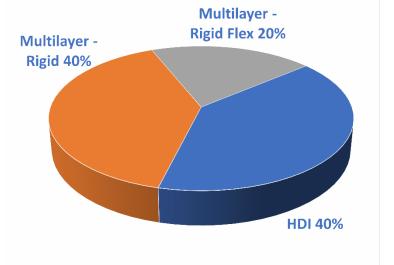


Technology

- Multilayers to 36+ Layers
- Flex Rigid to 18+ Layers
- High Performance Dielectrics
- LDI Laser Direct Imaging
- Blind & Buried Vias
- Micro Via Technology

- Conductive & Non-Conductive Via Fill
- Controlled Impedance
- Heat Sink Bonding
- Metal Core Constructions
- Alternative Surface Finishes
- Cavity and Cut-outs







Services & Capabilities

- NPI /Pilot Runs /Prototypes
- Low or Medium (L/M) Volume Productions
- KANBAN and VMI Program
- Impedance Modeling and TDR Testing
- Microsection and Detailed Analysis Reporting
- IST/HATS Analysis
- Electrical Testing (Fixture and Flying Probe)
- IPC-A-600 (Class 2 & 3), IPC 6012E/ES
- Quality Reporting- FAI & AS9102 FAIR
- DFM Seminars

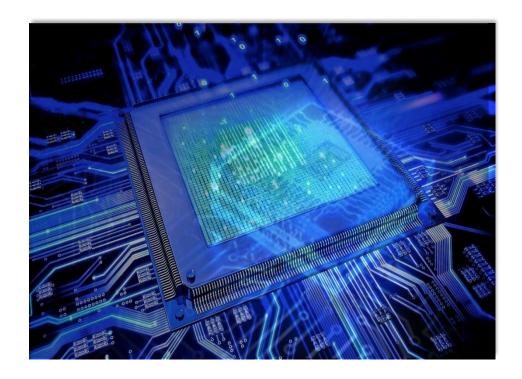




Technical Support

Engineering Services:

- DRC- Design Rules Check
- DFM- Design for Manufacturability
- Stack-up Data Reporting
- Cost Reduction Solutions- Value Engineering
- Frontline Genesis 2000 CAM Stations
- File Format: ODB++, Gerber, or 274X





| TECHNOLOGY ROADMAP | | | |
|---|----------------|----------------|---------------------------------------|
| Attribute | Standard | Advanced | Limited |
| Line/Space | | | |
| ½ oz Copper | 0.005"/0.005" | 0.004"/0.004" | < 0.003"/0.003" |
| 1 oz Copper | 0.006"/0.006" | 0.005"/0.005" | < 0.004"/0.004" |
| 2 oz Copper | 0.008"/0.008" | 0.007"/0.007" | < 0.006"/0.006" |
| Clearances (Plane Layers) | | | |
| Anti-Pad | Drill + 0.018" | Drill + 0.016" | <drill +="" 0.015"<="" td=""></drill> |
| Split Planes | 0.010" | 0.008" | < 0.007" |
| Drilling | | | |
| Minimum Hole Diameter | 0.008" | 0.006" | 0.005" |
| Maximum Hole Diameter | 0.255" | | |
| Aspect Ratio (Thickness : Hole Diameter) | 10:1 | 12:1 | 14:1 |
| Minimum Laser Via Hole | | | 0.004" |
| Laser Via Aspect Ratio | | | 1.5:1 |
| Laser Via Land Size (Diameter Over Drill) | | | 0.008" |
| Mechanical Drill Registration | ±0.003 | ±0.002 | |
| Routing | | | |
| Board Outline Tolerance | ± 0.005" | ± 0.004" | ±0.003 |
| Land Sizes | | | |
| Annular Ring (1-6 Layers) | 0.006" | 0.005" | < 0.004" |
| Annular Ring (8-10 Layers) | > 0.006" | 0.005" | < 0.004" |
| Annular Ring (> 12 Layers) | > 0.007" | 0.006" | < 0.005" |



| TECHNOLOGY ROADMAP | | | |
|---|-----------|-----------|-------------------|
| Attribute | Standard | Advanced | Limited |
| Board Thickness | | | |
| Minimum Core Thickness | 0.003" | 0.002" | 0.001" |
| Minimum Board Thickness | 0.008" | 0.004" | 0.0025" |
| Maximum Board Thickness | 0.125" | 0.200" | 0.250" |
| Thickness Tolerance | 10% | 8% | 5% |
| Maximum Layer Count | 28 | 30 | 36 |
| Maximum Copper Weight Internal Layers (oz./ft²) | 4 | 5-6 | >6 |
| Maximum Copper Weight External Layers (oz./ft²) | 4 | 5-6 | >6 |
| Board Size | | | |
| Maximum Panel Size | 18" x 24" | 21" x 24" | |
| Maximum Board Size | 16" x 22" | 18" x 22" | |
| Pitch | | | |
| SMT | 0.039" | 0.031" | 0.020" |
| BGA | > 0.020" | 0.016" | < 0.015" |
| Soldermask Dams | 0.004" | 0.003" | 0.002" (LDI Only) |
| Soldermask Clearance | 0.004" | 0.003" | 0.002" |
| Plated Through Hole Tolerance | ±0.003" | ±0.002" | |
| Non-Plated Hole Tolerance | ±0.002" | ±0.001" | |
| Impedance | | | |
| Impedance Tolerance | ± 10% | ± 5% | <± 5% |



| TECHNOLOGY ROADMAP | | | |
|--|----------|----------|--|
| Attribute | Standard | Advanced | |
| Via Construction | | | |
| Through Hole | Yes | Yes | |
| Blind (Mechanical) Sequential Lamination | Yes | Yes | |
| Buried (Mechanical) | Yes | Yes | |
| Laser Micro-Via | Yes | Yes | |
| Conical Drill | No | Yes | |
| Back Drilling | Yes | Yes | |
| Via Fill | | | |
| Non-Conductive Via Fill | Yes | Yes | |
| Conductive Via Fill | Yes | Yes | |
| Copper Fill Laser Drill | Yes | Yes | |



| TECHNOLOGY ROADMAP | | | |
|--|-----|-----|-----|
| High Tg FR4 > 170°C | | | |
| Isola FR-406 (170°C Tg) | YES | Yes | Yes |
| Isola 185HR (180°C Tg) | Yes | Yes | Yes |
| Isola IS-410 (180°C Tg) | Yes | Yes | Yes |
| Isola 370HR (180°C Tg) | Yes | Yes | Yes |
| ITEQ IT-180A (180°C Tg) | Yes | Yes | Yes |
| High Temperature Polyimide Materials | | | |
| Isola P95 And P96 (260°C Tg) | Yes | Yes | Yes |
| Arlon 85N (260°C Tg) | No | Yes | Yes |
| Arlon 85NT Thermount (250°C Tg/426°C Td) | No | Yes | Yes |
| Arlon 35N (250°C Tg) | No | Yes | Yes |
| Arlon 55N (170°C Tg) | No | Yes | Yes |
| Arlon 55NT (250°C Tg) | No | Yes | Yes |
| Arlon 33N (250°C Tg) | No | Yes | Yes |
| High Frequency Materials | | | |
| Isola FR408 (180°C Tg) | Yes | Yes | Yes |



| TECHNOLOGY ROADMAP | | | |
|---|----------|----------|---------|
| attribute | Standard | Advanced | Limited |
| ligh Frequency Materials | | | |
| ITEQ 200LK (200°C Tg) | Yes | Yes | Yes |
| Isola FR408HR High Tg (190°C)/Low Dk 3.8 | Yes | Yes | Yes |
| Nelco 4000-13 High Tg (210°C) /Low Dk 3.7 | Yes | Yes | Yes |
| Rogers 3000, 4000, 5000 & 6000 Series | Yes | Yes | Yes |
| Arlon 25 and 49 Series | Yes | Yes | Yes |
| PTFE/Teflon® and Taconic | Yes | Yes | Yes |
| Panasonic Megtron4, 6 and 7 | Yes | Yes | Yes |
| urface Finishes | | | |
| ENIG | Yes | Yes | Yes |
| ENEPIG | | Yes | Yes |
| HASL (Eutectic Solder) | Yes | Yes | Yes |
| Lead-Free HAL (RoHS Approved) | Yes | Yes | Yes |
| Immersion Silver | Yes | Yes | Yes |
| Immersion Tin | Yes | Yes | Yes |
| Electrolytic Nickel/Gold | Yes | Yes | Yes |



| TECHNOLOGY ROADMAP | | | |
|--------------------|---------------------|---|--|
| Standard | Advanced | Limited | |
| | | | |
| Yes | Yes | Yes | |
| | Yes Yes Yes Yes Yes | Yes | |



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